

In the claims:

Claims 1 - 8 (Canceled).

9. (Previously presented) An edge seal around the periphery of an integrated circuit device comprising:

a semiconductor substrate;

a layer of low-k dielectric material over the semiconductor substrate;

a layer of hard material over or under the layer of low-k dielectric material, the layer of hard material selected from the group consisting of a dielectric material and a hard mask material; and

an edge seal structure around the periphery of an integrated circuit device comprising:

a metallic wall of a high conductivity metal in the layer of low-k dielectric material and in the layer of hard material; and

a layer of insulation material on sidewalls of the metallic wall between the metallic wall and the low-k dielectric material and between the metallic wall and the layer of hard material, wherein the insulation material and low-k dielectric material are different materials and wherein the insulation material is selected from the group consisting of  $\text{SiO}_2$ ,  $\text{SiC}$ ,  $\text{Si}_3\text{N}_4$ ,  $\text{Al}_2\text{O}_3$ , diamond like carbon, polyimide and combinations thereof.

10. (Original) The edge seal of claim 9 wherein the low-k dielectric material comprises SiLK or fluoridized polyimide.

11. (Previously presented) The edge seal of claim 9 wherein the layer of hard material comprises a bottom layer on the semiconductor substrate under the low-k dielectric material and a top moisture barrier on the low-k dielectric material.

Claim 12. (Canceled)

13. (Original) The edge seal of claim 9 further comprising a barrier layer between the metallic wall and the insulation material wherein the barrier layer is selected from the group consisting of tantalum, tantalum nitride, chromium/ chromium oxide, titanium, titanium nitride, tungsten silicide and combinations thereof.

14. (Original) The edge seal of claim 9 wherein the high conductivity metal is copper.

15. (Original) The edge seal of claim 9 wherein the thickness of the insulation material is 0.05 microns to 0.5 microns.

Claims 16 - 18 (Canceled).